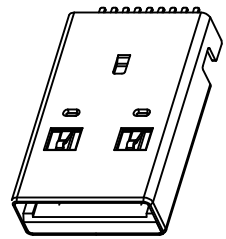
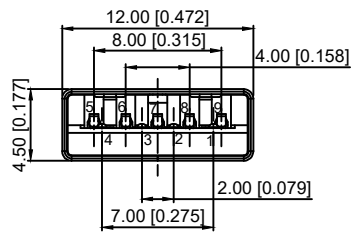


RECOMMENDED PCB LAYOUT



Material
 Housing Material: LCP, UL94V-0, blue
 Contact Terminal: Copper Alloy
 Metallic Shell: Spcc
 Plating
 Underplating: Nickel
 Contact Plating: 1μ" Gold
 Solder Tail: 100μ" Min. Tin
 Metallic Shell: Nickel
Electrical
 Voltage Rating: 100 V AC
 Current Rating: 0.25A (Signal pins 2,3,5,6,7,8,9) 1.8A (Power Pins 1,4)
 Contact Resistance: 30mΩ Max.
 Insulation resistance: 1000MΩ Min.
 Dielectric withstanding voltage: 100V AC/Minute
Mechanical
 Mating Force: 35N (3.57KgF) Max
 Unmating Force: 10N (1.02KgF) Min. initial, 8N min after test
 Environmental and Processing
 Operating Temperature: -40°C to +85°C

Pin #	SIGNAL NAME	DESCRIPTION	MATING SEQUENCE
1	VBUS	POWER	SECOND
2	D-	USB 2.0 DIFFERENTIAL PAIR	THIRD
3	D+		
4	GND	GROUND FOR POWER RETURN	SECOND
5	SsIA_SSRX-	SUPERSPEED RECEIVER DIFFERENTIAL PAIR	LAST
6	SsIA_SSRX+		
7	GND_DRAIN	GROUND FOR SIGNAL RETURN	
8	SsIA_SSTX-	SUPERSPEED TRANSMITTER DIFFERENTIAL PAIR	
9	SsIA_SSTX+		
Shell	Shield	CONNECTOR METAL SHELL	FIRST

U237-09XN-4BLVS10-1
 1:Au 1U"
 5:Au 15U"
 6:Au 30U"
 T:TIN
 N:NICKEL
 1: SPCC
 B:BLACK W:WHITE BL:BLUE
 1:PBT
 2:PA6T
 3:PA9T
 4:LCP

REVISIONS					UNSPECIFIED TOLERANCES	DSND	DATE	SCALE: N/A	MODEL TYPE: USB 3.0
ΔX				ANGLAR	±5°	DWN	DATE	VIEW:	PART NO.:
Δx				L ≤ 4	±0.2	CHKD	DATE	UNIT: mm/in	DWG NO.:
Δx				4 < L ≤ 16	±0.3	APPD	DATE	SIZE: A4	U237-09XN-4BLVS10-1
MARK	DESCRIPTION	DATE	REVISED	16 < L ≤ 63	±0.4				WEIGHT
				L > 63	±0.5				SHEET
									REVISION
									1.0g
									1/1
									A0